



CONNECTORS

BOARD-TO-BOARD HEADERS & RECEPTACLES



✓ Active

TE CONNECTIVITY (TE)

Assy, pin, 60 psn, 30 Au, tin, Mezalok

[Mezalok](#) | [Mezalok](#)

2102079-3

TE Internal Number: 2102079-3

Not EU RoHS Compliant

Not EU ELV Compliant

Connector Style Plug

Number of Positions 60

Centerline (Pitch) 1.27 mm [.05 in]

Stack Height (mm) 10, 12, 18

Stack Height (in) .393, .4716, .7074

Packaging Method Tape & Reel

[↓ PRODUCT DRAWING](#)
English

[↓ 3D PDF](#)

DOCUMENTATION

Product Drawings

ASSEMBLY, PIN, 60 POSITION, MEZALOK STACKING CONNECTOR

PDF

English

CAD Files

3D PDF

PDF

3D

Customer View Model

2D_DXF.ZIP

English

Customer View Model

3D_IGS.ZIP

English

Customer View Model

3D_STP.ZIP

English

Product Specifications

Product Specification

Product Specification For The Mezalok Stacking Connector System

PDF

English

Qualification Test Report

MEZALOK* Stacking Connector System

PDF

English

Design For Environment Standard

Mezalok Stacking Connectors

PDF

English

FEATURES



Please review product documents or [contact us](#) for the latest agency approval information.

Please Note: Use the Product Drawing for all design activity.

Product Type Features

Connector Style Plug

Sealable No

Connector & Contact Terminates To Printed Circuit Board

Gasket Without

Stabilizers Without

Row-to-Row Spacing 1.27 mm [.0499 in]

Series Mezalok

PCB Mounting Orientation Vertical

Connector Type Connector Assembly

Boss Without

Hybrid No

Strain Relief Without

Product Type Connector

Configuration Features

Stackable Yes

Number of Positions 60

Number of Rows 6

Electrical Characteristics

Dielectric Withstanding Voltage (VAC) 750

Voltage (VAC) 250

Insulation Resistance (MΩ) 1000

Body Features

Color Natural

Contact Features

Contact Protection Without

Contact Shape Square

Contact Mating Area Plating Material Gold

Contact Mating Area Plating Thickness .76 μm [29.9212 μin]

Contact Layout Matrix

Contact Base Material Phosphor Bronze

Contact Type Pin

Termination Features

Termination Method to PC Board Surface Mount - Solder Ball

Solder Ball Material Tin-Lead

Mechanical Attachment

PCB Mount Retention Without

Housing Features

Centerline (Pitch) 1.27 mm [.05 in]

Housing Material LCP (Liquid Crystal Polymer)

Housing Color Natural

Dimensions

Stack Height (mm) 10, 12, 18

Stack Height (in) .393, .4716, .7074

Height 9.15 mm [.359595 in]

Usage Conditions

Operating Temperature Range -55 – 125 °C [-67 – 257 °F]

Operation/Application

Assembly Process Feature None

Pick and Place Cover With

For Use With Socket Housing

Industry Standards

Industry Standard Configuration None

Industry Standard None

Packaging Features

Packaging Method Tape & Reel

Packaging Quantity 230

PRODUCT COMPLIANCE



Statement of Compliance

Statement of Compliance

PDF
